

IMPORTANT DATES

January 14, 2022

- Tutorial Proposal Submission Deadline
- Focused Session Proposal Submission Deadline

January 21, 2022

- Tutorial Proposal Submission Acceptance
- Focused Session Proposal Submission Acceptance

February 14, 2022

Initial Paper Submission Deadline

March 31, 2022

Notification of Acceptance

April 10, 2022

Final Manuscript Submission Deadline

June 10, 2021

Open Preview Publication Accessible
Through IEEE Xplore

June 14, 2022

Standard Registration Deadline

CALL FOR PAPERS

The IEEE International Conference on Flexible, Printable Sensors and Systems (FLEPS 2022) will be held in Vienna, Austria.

IEEE FLEPS 2022 is intended to provide a forum for research scientists, engineers, and practitioners throughout the world to present their latest research findings, ideas, and applications in the area of Flexible and Printable Sensors and Systems.

TOPICS OF INTEREST

- » Organic/Inorganic Electronic Sensors
- » Emerging Materials for Flexible and Printable Systems
- » Manufacturing Techniques
- » High-throughput Printable Electronics
- » Hybrid Flexible Sensors and Electronics
- » Stretchable/Shrinkable Sensors and Electronics
- » Soft/Smart Wearable and Implantable Sensing Systems
- » Disposable/Reusable Sensors and Electronics
- » Printed Large-Area Sensors and Systems
- » Flexible or Printed Active and Passive Components (e.g. actuators, printed energy devices, smart labels, RFID etc.)
- » Emerging applications of Flexible Electronics inc. IoT, smart cities etc.
- » Simulation and Modelling
- » Flexible/Printable Electronics in context with Circular Economy and green electronics

PUBLICATION OF PAPERS

Presented papers will be included in the Proceedings of IEEE FLEPS 2022 and in IEEE Xplore pending author requirements being met. Authors may submit an extended IEEE FLEPS 2022 papers to the Special Journal Issue in the IEEE Journal on Flexible Electronics (J-FLEX).

EXHIBITION & PATRON OPPORTUNITIES

The Conference exhibit area will provide your company or organization with the opportunity to inform and display your latest products, services, equipment, books, journals, and publications to attendees from around the world.

For further information, contact **Coral Miller** at Conference Catalysts, LLC.

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